



LIGITEK

LIGITEK ELECTRONICS CO.,LTD.
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ROUND TYPE LED LAMPS



Lead-Free Parts

LDBK2043-W73

DATA SHEET

DOC. NO : QW0905-LDBK2043-W73

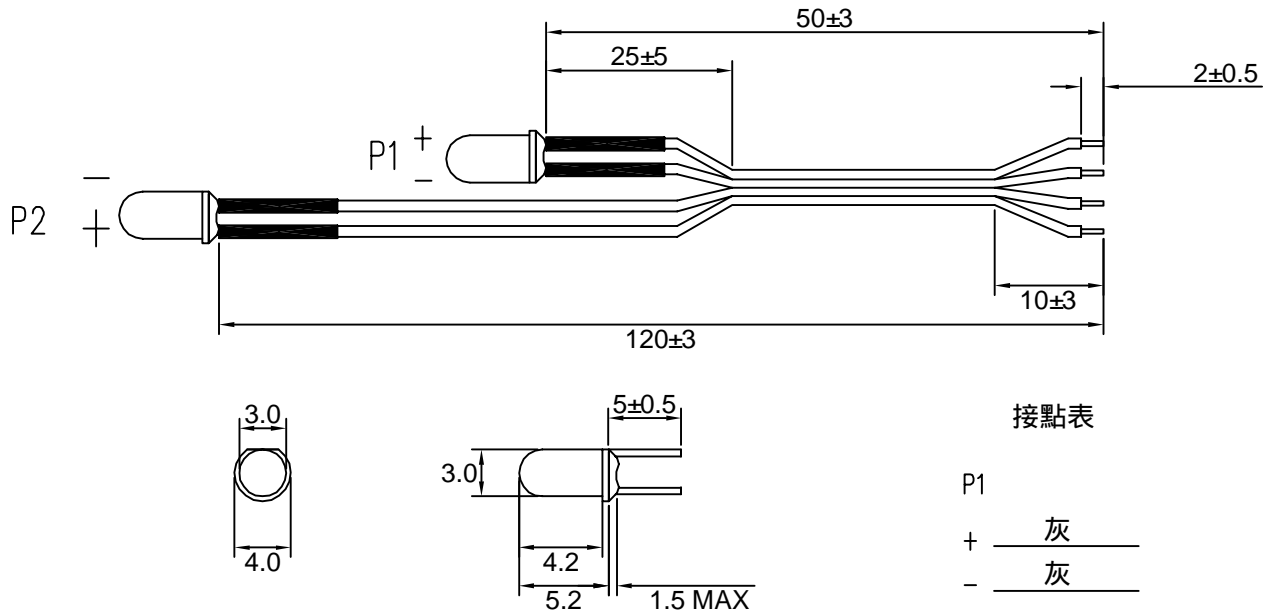
REV. : C

DATE : 31 - Mar. - 2009





Package Dimensions

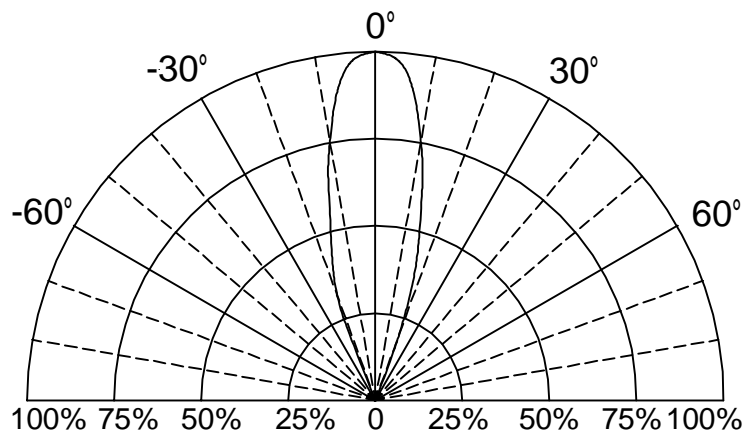


接點表

P1	
+	灰
-	灰
P2	
-	灰
+	灰

Note : 1.All dimension are in millimeter tolerance is ± 0.25 mm unless otherwise noted.
2.Specifications are subject to change without notice.

Directivity Radiation





Absolute Maximum Ratings at Ta=25

Parameter	Symbol	Ratings	UNIT
		DBK	
Forward Current	IF	30	mA
Peak Forward Current Duty 1/10@10KHz	IFP	100	mA
Power Dissipation	PD	120	mW
Reverse Current @5V	Ir	50	μ A
Electrostatic Discharge(*)	ESD	500	V
Operating Temperature	Topr	-20 ~ +80	
Storage Temperature	Tstg	-30 ~ +100	

* Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrosatic glove is recommended when handing these LED. All devices, equipment and machinery must be properly grounded.

Typical Electrical & Optical Characteristics (Ta=25)

PART NO	MATERIAL	COLOR		Dominant wave length Dnm		Spectral halfwidth nm	Forward voltage @ 2 mA(V)		Luminous intensity @2mA(mcd)		Viewing angle 2 1/2 (deg)
		Emitted	Lens	Typ.	Max.		Typ.	Max.	Min.	Typ.	
LDBK2043-W73	InGaN/GaN	Blue	Water Clear	468	477	30	3.0	3.5	300	700	30

Note : 1.The forward voltage data did not including $\pm 0.1V$ testing tolerance.
2. The luminous intensity data did not including $\pm 15\%$ testing tolerance.



Brightness Code For Standard LED Lamps

DBK CHIP

Group	Luminous Intensity(mcd) at 2 mA	
	Min.	Max.
A16	300	350
A17	350	450
A18	450	550
A19	550	700

Color Code

DBK CHIP

Group	Wave length(nm) at 2 mA	
	Min.	Max.
OC	468	471
OB	471	474
OA	474	477



Typical Electro-Optical Characteristics Curve

DBK CHIP

Fig.1 Forward current vs. Forward Voltage

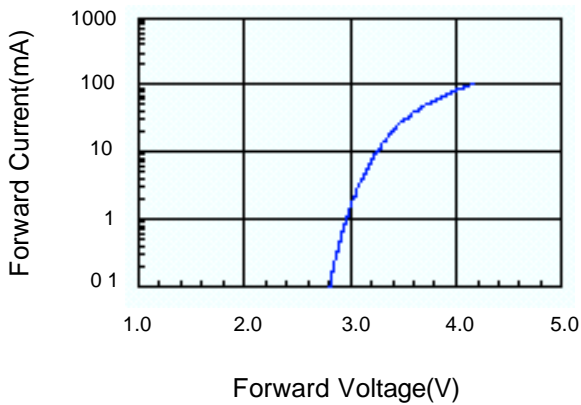


Fig.2 Relative Intensity vs. Forward Current

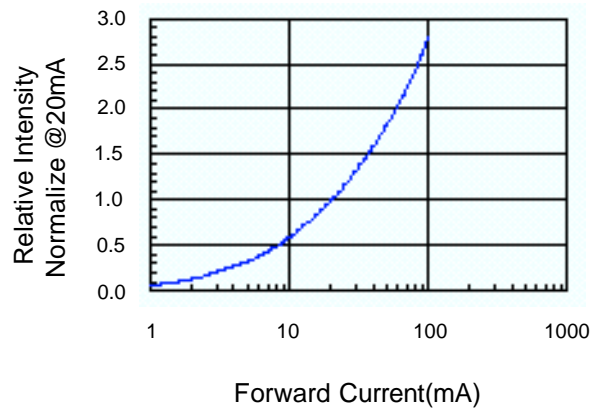


Fig.3 Forward Voltage vs. Temperature

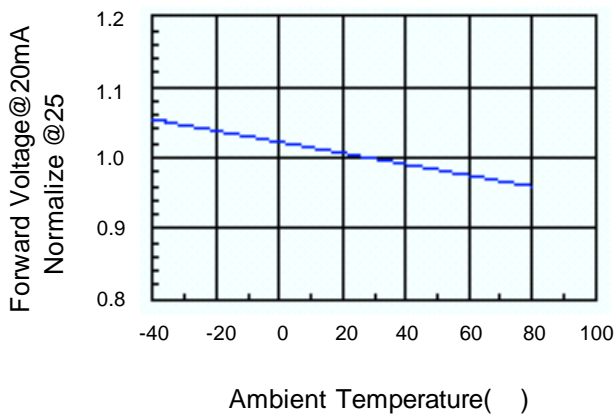


Fig.4 Relative Intensity vs. Temperature

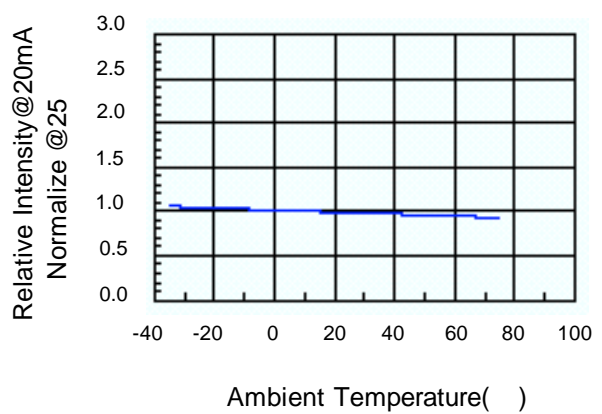
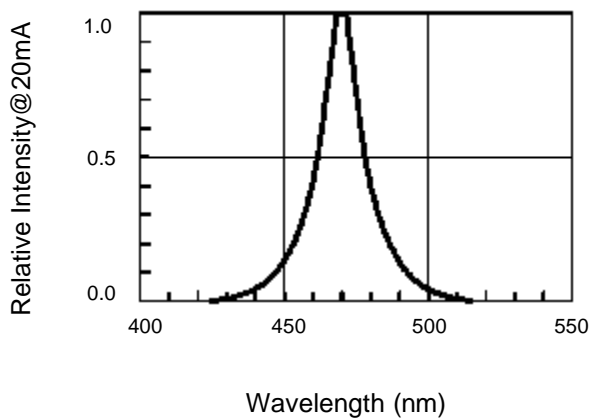


Fig.5 Relative Intensity vs. Wavelength





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PART NO. LDBK2043-W73

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Soldering Condition(Pb-Free)

1.Iron:

Soldering Iron:30W Max

Temperature 350 ° C Max

Soldering Time:3 Seconds Max(One time only)

Distance:2mm Min(From solder joint to body)

**Reliability Test:**

Test Item	Test Condition	Description	Reference Standard
Operating Life Test	1.Under Room Temperature 2.If=20mA 3.t=1000 hrs (-24hrs, +72hrs)	This test is conducted for the purpose of determining the resistance of a part in electrical and thermal stressed.	MIL-STD-750: 1026 MIL-STD-883: 1005 JIS C 7021: B-1
High Temperature Storage Test	1.Ta=105 ±5 2.t=1000 hrs (-24hrs, +72hrs)	The purpose of this is the resistance of the device which is laid under condition of high temperature for hours.	MIL-STD-883:1008 JIS C 7021: B-10
Low Temperature Storage Test	1.Ta=-40 ±5 2.t=1000 hrs (-24hrs, +72hrs)	The purpose of this is the resistance of the device which is laid under condition of low temperature for hours.	JIS C 7021: B-12
High Temperature High Humidity Test	1.Ta=65 ±5 2.RH=90%~95% 3.t=240hrs ±2hrs	The purpose of this test is the resistance of the device under tropical for hours.	MIL-STD-202:103B JIS C 7021: B-11
Thermal Shock Test	1.Ta=105 ±5 & -40 ±5 (10min) (10min) 2.total 10 cycles	The purpose of this is the resistance of the device to sudden extreme changes in high and low temperature.	MIL-STD-202: 107D MIL-STD-750: 1051 MIL-STD-883: 1011
Solder Resistance Test	1.T.Sol=260 ±5 2.Dwell time= 10 ±1sec.	This test intended to determine the thermal characteristic resistance of the device to sudden exposures at extreme changes in temperature when soldering the lead wire.	MIL-STD-202: 210A MIL-STD-750: 2031 JIS C 7021: A-1
Solderability Test	1.T.Sol=230 ±5 2.Dwell time=5 ±1sec	This test intended to see soldering well performed or not.	MIL-STD-202: 208D MIL-STD-750: 2026 MIL-STD-883: 2003 JIS C 7021: A-2